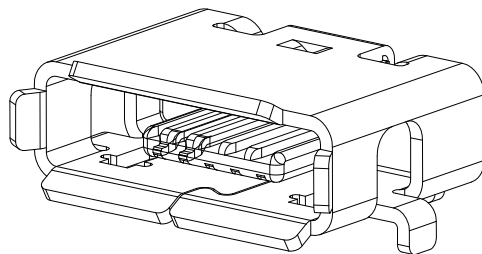
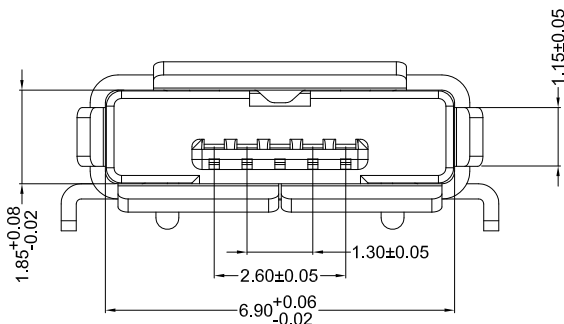
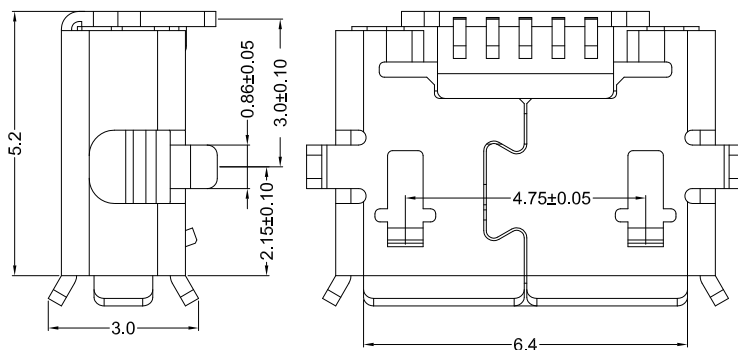
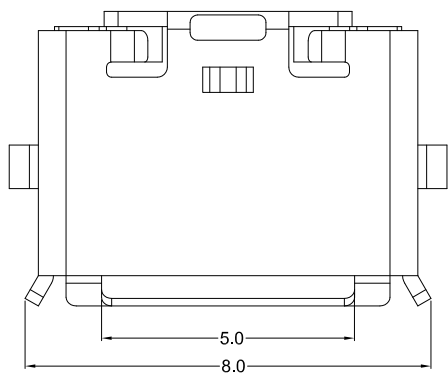


PCB LAYOUT



NOTES:

1. Material:

Housing: High Temperature Thermoplastic+G.F, UL 94V-0 Rated.
 Color: Black.
 Contact: Copper Alloy, T=0.15mm.
 Plating: Gold Plating over Nickel on Contact Area,
 Tin Plating on Solder Tail.
 Shield: Stainless Steel (SUS).
 Plating: Nickel Plating.

2. Mechanical:

Insertion Force: 3.57Kgf Max.
 Withdrawal Force: 1.0Kgf Min Initial, 0.81~2.05Min after 10000Cycles.
 Durability: 10,000cycles.

3. Electrical Specification:

Current Rating: 1.0Ampere at 30VDC.
 Contact Resistance: 30mΩ Max Initial, 40mΩ after 1000Cycles.
 Insulation Resistance: 100MΩ Min.
 Dielectric Withstanding Voltage: 100V AC for 1Min.

4. Environmental:

Operating Temperature: -30°C to +80°C

Part Number:

CU2M-R05RSG0-R6

USB 2.0 Micro Series
 R: Receptacle Type
 05: 5Pins
 R: Right Angle

Product Number:
 R6: Micro AB, Reversed Type
 0: Black Color
 G: Gold Flash Plating
 S: SMT Type

A	07/21/11	RELEASED FOR PRODUCTION	
REV	DATE	DESCRIPTION	
UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MM. TOLERANCES ARE:		 凱聯科技股份有限公司 Conn-Link Technology Inc.	
DECIMALS	ANGLES		
.X ± .38	± 3°		
.XX ± .25			
.XXX ± .20			
DO NOT SCALE DRAWING	SHEET 1 OF 1	SCALE NONE	DWG. NO. CU2M-R05-0R6